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(54) DOUBLE-SIDED REDISTRIBUTION LAYER (RDL) SUBSTRATE FOR PASSIVE AND **DEVICE INTEGRATION**

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(57)**ABSTRACT**

A device includes a redistribution layer (RDL) substrate. The device also includes a passive component in the RDL substrate proximate a first surface of the RDL substrate. The device further includes a first die coupled to a second surface of the RDL substrate, opposite the first surface of the RDL substrate.

